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Semiconductor devices – Integrated circuits –

Part 23-4: Hybrid integrated circuits and film structures – Manufacturing line certification – Blank detail specification

Dispositifs à semiconducteurs – Circuits intégrés –

Partie 23-4: Circuits intégrés hybrides et structures par films – Certification de la ligne de fabrication – Spécification particulière cadre

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES – INTEGRATED CIRCUITS –

Part 23-4: Hybrid integrated circuits and film structures – Manufacturing line certification – Blank detail specification

FOREWORD

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International Standard IEC 60748-23-4 has been prepared by subcommittee 47A: Integrated circuits, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the European standard EN 165000-4 and the following documents:

FDIS	Report on voting
47A/641/FDIS	47A/652/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

IEC 60748-23-4 should be read in conjunction with Parts 23-1, 23-2 and 23-3.

The QC number that appears on the front cover of this publication is the specification number in the IEC Quality Assessment System for Electronic Components (IECQ).

The committee has decided that the contents of this publication will remain unchanged until 2006. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

SEMICONDUCTOR DEVICES – INTEGRATED CIRCUITS –

Part 23-4: Hybrid integrated circuits and film structures – Manufacturing line certification – Blank detail specification

1 General

1.1 Scope

This part of IEC 60748 serves as a Blank Detail Specification (BDS) for a high quality approval system and contains requirements for style and layout and minimum content of detail specifications. These requirements are applicable when the detail specification is published (e.g. for standard product).

1.2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60748-23-1:2002, *Semiconductor devices – Integrated circuits – Part 23-1: Hybrid integrated circuits and film structures – Manufacturing line certification – Generic specification*

IEC 60748-23-2:2002, *Semiconductor devices – Integrated circuits – Part 23-2: Hybrid integrated circuits and film structures – Manufacturing line certification – Internal visual inspection and special tests*

IEC 60748-23-3:2002, *Semiconductor devices – Integrated circuits – Part 23-3: Hybrid integrated circuits and film structures – Manufacturing line certification – Manufacturers' self audit check list and report*